

# RSJ151P10

## Pch 100V 15A Power MOSFET

$V_{DSS}$	-100V
R <sub>DS(on)</sub> (Max.)	120m $Ω$
I <sub>D</sub>	-15A
$P_D$	50W

## ● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

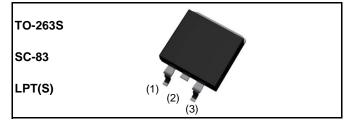
## Application

Switching Power Supply

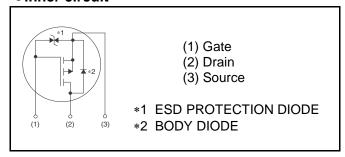
**Automotive Motor Drive** 

Automotive Solenoid Drive

### Outline



## ●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	RSJ151P10

## •Absolute maximum ratings( $T_a = 25$ °C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	-100	V
Continuous drain surrent	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±15	A
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±8	А
Pulsed drain current	I <sub>D,pulse</sub> *2	±30	А	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche energy, single pulse		E <sub>AS</sub> *3	33	mJ
Avalanche current		I <sub>AR</sub> *3	<b>–15</b>	А
Power dissipation	$T_c = 25$ °C	P <sub>D</sub>	50	W
$T_a = 25^{\circ}C^{*4}$		P <sub>D</sub>	1.35	W
Junction temperature		T <sub>j</sub>	150	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Symbol	Values			Unit
	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	$R_{thJC}$	-	-	2.5	°C/W
Thermal resistance, junction - ambient *4	$R_{thJA}$	-	-	92.6	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## •Electrical characteristics( $T_a = 25$ °C)

Parameter	Symbol	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = -1mA$	-100	ı	ı	V
		$V_{DS} = -100V, V_{GS} = 0V$			4	
Zoro gata valtaga drain aurrant		$T_j = 25^{\circ}C$	-	-	_1	μА
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = -100V, V_{GS} = 0V$			-100	
		T <sub>j</sub> = 125°C	-	-		
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±10	μΑ
Gate threshold voltage	$V_{GS (th)}$	$V_{DS} = -10V, I_{D} = -1mA$	-1.0	ı	-2.5	V
		$V_{GS} = -10V, I_D = -15A$	ı	85	120	
		$V_{GS} = -4.5V, I_D = -15A$	-	95	135	
Static drain - source on - state resistance	$R_{DS(on)}^{}^{\star5}}$	$V_{GS} = -4.0V, I_D = -15A$	-	100	140	mΩ
		$V_{GS} = -10V, I_D = -15A$		155	220	
		T <sub>j</sub> = 125°C	-	155	220	
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = -10V, I_{D} = -15A$	13	26	-	S

## ●Electrical characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii e lei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	3800	1	
Output capacitance	C <sub>oss</sub>	$V_{DS} = -25V$	-	160	1	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	100	1	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq -50V, V_{GS} = -10V$	-	30	1	
Rise time	t <sub>r</sub> *5	$I_D = -7.5A$	-	40	-	nc
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L = 12\Omega$	-	165	-	ns
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	95	-	

## • Gate Charge characteristics ( $T_a = 25$ °C)

Doromotor	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*5}$	$V_{DD} \simeq -50V$	-	64	-	
Gate - Source charge	Q <sub>gs</sub> *5	$I_D = -15A$	-	10	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	$V_{GS} = -10V$	-	10	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq -50V, I_D = -15A$	-	-3.1	-	V

## ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	I <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	-	-15	Α
Pulsed source current	I <sub>SM</sub> *2	1 <sub>c</sub> = 25 C	ı	ı	-30	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = -15A$	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = -15A	1	60	1	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = -100A/μs	-	145	-	μС

<sup>\*1</sup> Limited only by maximum temperature allowed.

\*5 Pulsed

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\simeq}$  200 $\mu$ H,  $V_{DD}$  = -50V, Rg =  $10\Omega$ , starting  $T_{j}$  =  $25^{\circ}C$ 

<sup>\*4</sup> Mounted on a epoxy PCB FR4 (20mm × 30mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

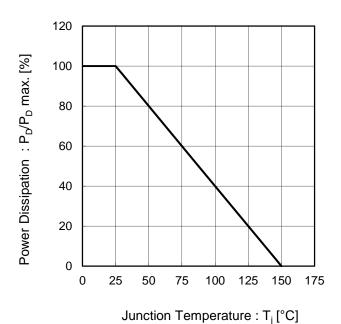
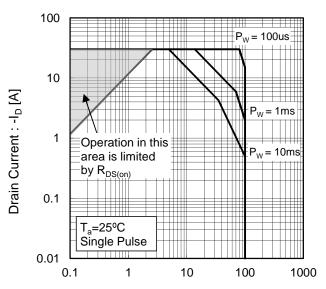
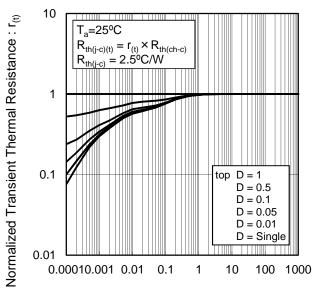


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: P<sub>W</sub>[s]

Fig.4 Avalanche Current vs Inductive Load

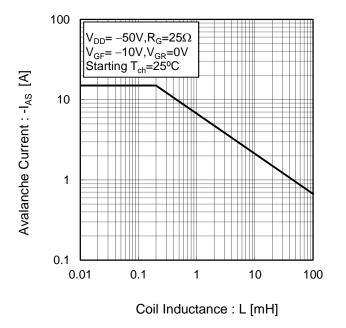
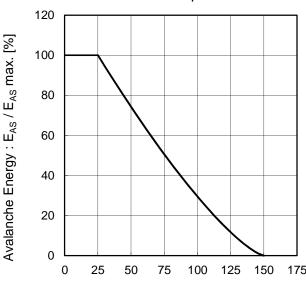
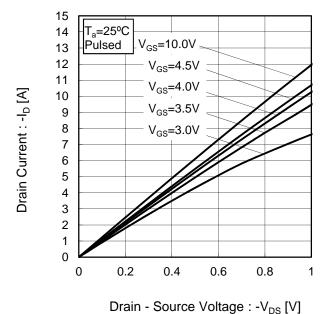


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



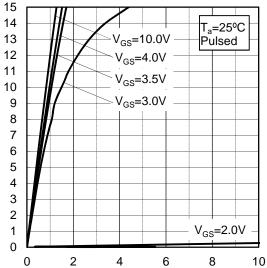
Junction Temperature : T<sub>i</sub> [°C]

Fig.6 Typical Output Characteristics(I)



Drain Current : -I<sub>D</sub> [A]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : -V<sub>DS</sub> [V]

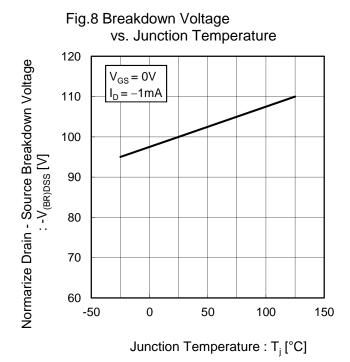
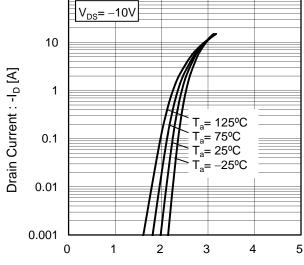


Fig.9 Typical Transfer Characteristics 100  $V_{DS} = -10V$ 10



Gate - Source Voltage : -V<sub>GS</sub> [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature

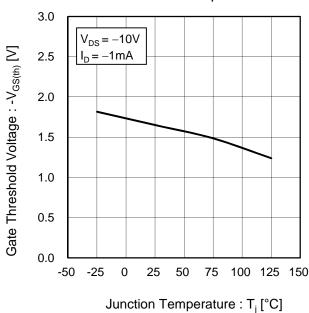
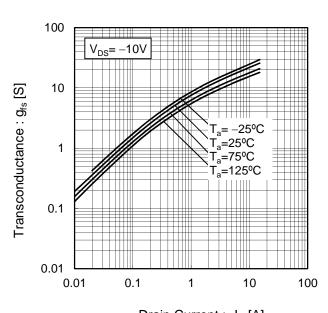


Fig.11 Transconductance vs. Drain Current



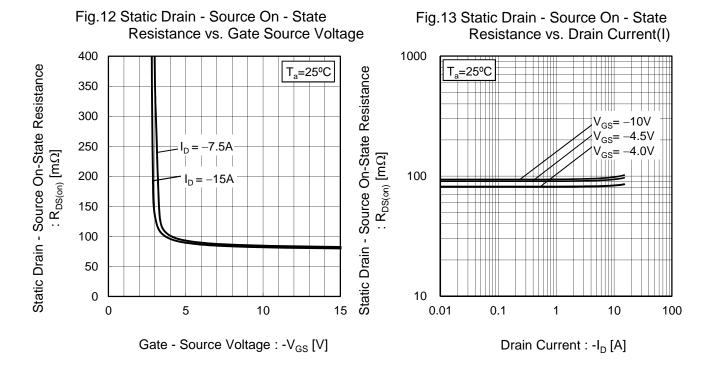
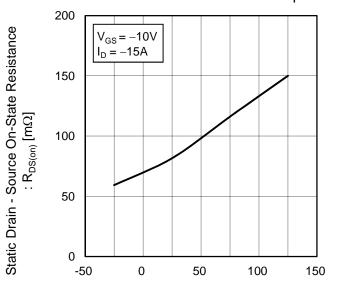


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature :  $T_j$  [°C]

Resistance vs. Drain Current(II)

1000  $V_{GS} = -10V$   $V_{GS} = -10V$ 

Drain Current : -I<sub>D</sub> [A]

Fig.15 Static Drain - Source On - State

Fig.16 Static Drain - Source On - State
Resistance vs. Drain Current(III)

1000

V<sub>GS</sub> = -4.5V

T<sub>a</sub> = 125°C

T<sub>a</sub> = 75°C

T<sub>a</sub> = 25°C

T<sub>a</sub> = -25°C

T<sub>a</sub> = -25°C

T<sub>a</sub> = -25°C

T<sub>a</sub> = -25°C

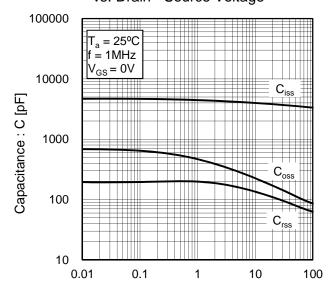
Drain Current: -I<sub>D</sub> [A]

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV) 1000 Static Drain - Source On-State Resistance =75°C =25°C –25°C  $: R_{DS(on)} [m\Omega]$ 100 10 0.01 0.1 1 10 100 Drain Current : -I<sub>D</sub> [A]

120 100 Drain Current Dissipation : I<sub>D</sub>/I<sub>D</sub> max. (%) 80 60 40 20 0 25 50 75 100 125 175 0 150 Junction Temperature : T<sub>i</sub> [°C]

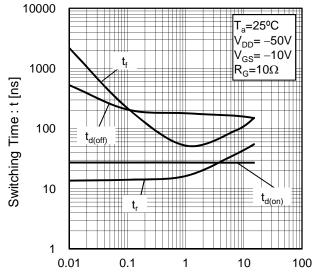
Fig.18 Drain Current Derating Curve

Fig.19 Typical Capacitance vs. Drain - Source Voltage



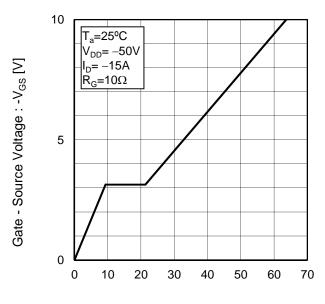
Drain - Source Voltage : - $V_{DS}$  [V]

Fig.20 Switching Characteristics



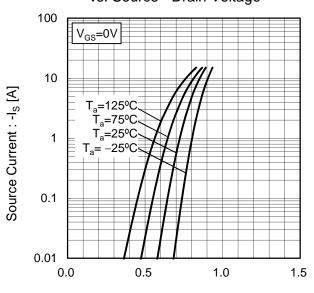
Drain Current : -I<sub>D</sub> [A]

Fig.21 Dynamic Input Characteristics



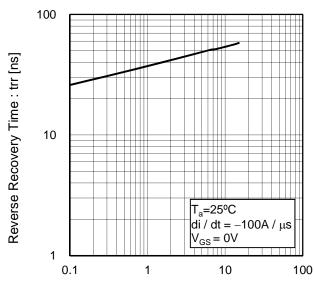
Total Gate Charge : Q<sub>g</sub> [nC]

Fig.22 Source Current vs. Source - Drain Voltage



Source-Drain Voltage: -V<sub>SD</sub> [V]





Source Current : -I<sub>S</sub> [A]

## ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

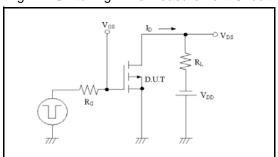


Fig.2-1 Gate Charge Measurement Circuit

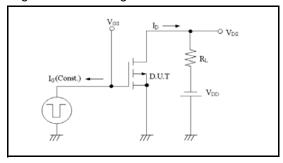


Fig.3-1 Avalanche Measurement Circuit

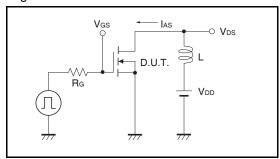


Fig.1-2 Switching Waveforms

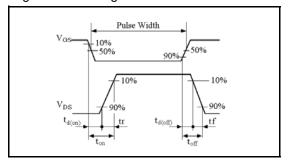


Fig.2-2 Gate Charge Waveform

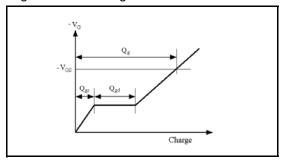
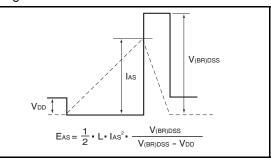
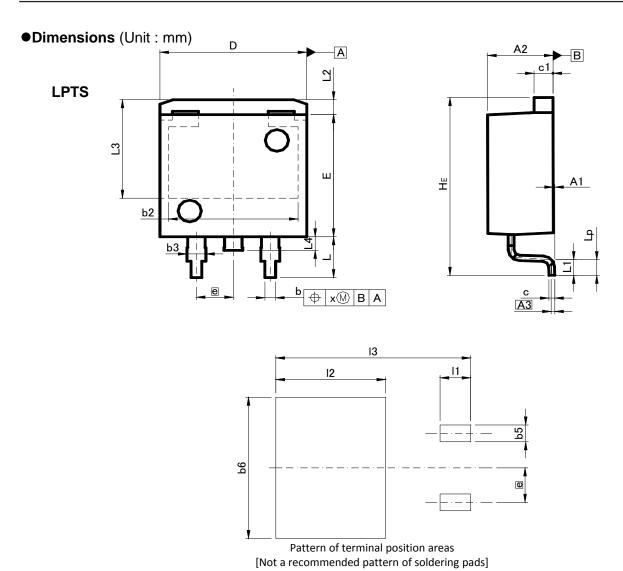


Fig.3-2 Avalanche Waveform





DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	110
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	0.90	1.50	0.035	0.059
L2	1.10		0.0	143
L3	7.25		0.285	
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.010

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
bb	-	1.23	-	0.049
b6	_	10.40	-	0.409
- 11	-	2.10	-	0.083
12	-	7.55	-	0.297
13	_	13.40	_	0.528

Dimension in mm / inches

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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [h] Use of the Products in places subject to dew condensation
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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For details, please refer to ROHM Mounting specification

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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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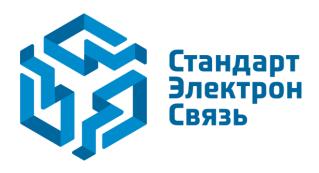
Part Number	RSJ151P10
Package	LPTS (D2PAK)
Unit Quantity	1000
Minimum Package Quantity	1000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes

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